Announcement and Call for Abstracts
Topical Workshop on
Wafer Level Packaging

This workshop is being held as a part of the Device Packaging Conference

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Wafer Level Packaging Workshop Focus: The objective of the Wafer Level Packaging Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Wafer Level Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to these new packaging technologies. Abstracts are being requested on the following topics:

- Redistribution and Repassivation
- Under Bump Metallization
- WLSCP Solder Bumping
- Wafer Thining
- Backside Coating
- Laser Marking
- Dicing
- Testing and Modeling
- Mechanical, Thermal and Electrical
- Board Level Reliability
- Tight Pitch (0.3mm) WL CSP
- Fan-Out CSP Technologies
- Applications

The Wafer Level Packaging & Flip Chip Technologies Workshops will also be organizing an evening Panel Session, in conjunction with the WL CSP Forum (www.wlcspforum.org).

Those wishing to present to the Wafer Level Packaging Workshop sector of the Device Packaging Conference must submit a 200-300 word abstract electronically no later than December 3, 2010, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to six-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 28, 2011. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Wafer Level Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 3, 2011 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 7th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at: www.imaps.org/pdc no later than December 3, 2010.